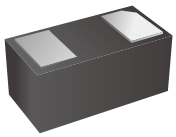
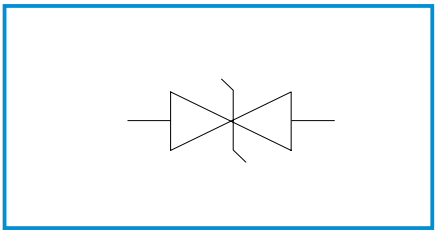
1-Line Ultra Low Capacitance Bi-directional TVS Diode

Features



- Ultra small package: 1.0x0.6x0.5mm
- Ultra low capacitance: 0.3pF typical
- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- AEC-Q101 qualified
- Complies with following standards:
  - – IEC 61000-4-2 (ESD) immunity test
    - Air discharge: ±25kV
    - Contact discharge: ±22kV
  - – IEC61000-4-5 (Lightning) 4A (8/20μs)
- RoHS Compliant
- Marking: 21

Functional Diagram



Applications

- Cellular Handsets and Accessories
- Display Ports
- MDDI Ports
- USB Ports
- Digital Visual Interface (DVI)
- PCI Express and Serial SATA Ports

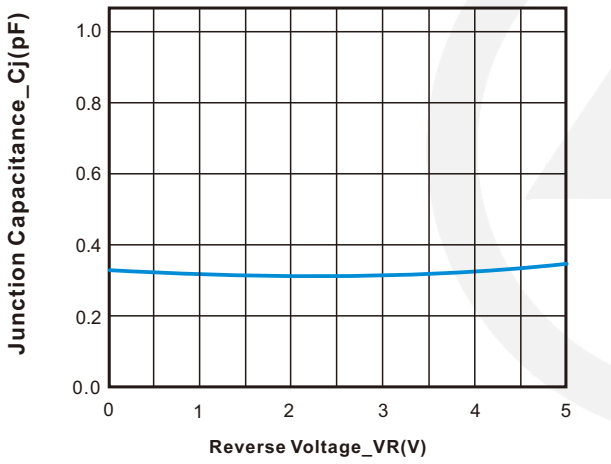
Absolute Maximum Ratings (Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20μs)	Ppk	100	W
Peak Pulse Current (8/20μs)	I_{PP}	4	A
ESD per IEC 61000−4−2 (Air) ESD per IEC 61000−4−2 (Contact)	V_{ESD}	±25 ±22	kV
Operating Temperature Range	T_J	−55 to +125	°C
Storage Temperature Range	Tstg	−55 to +150	°C

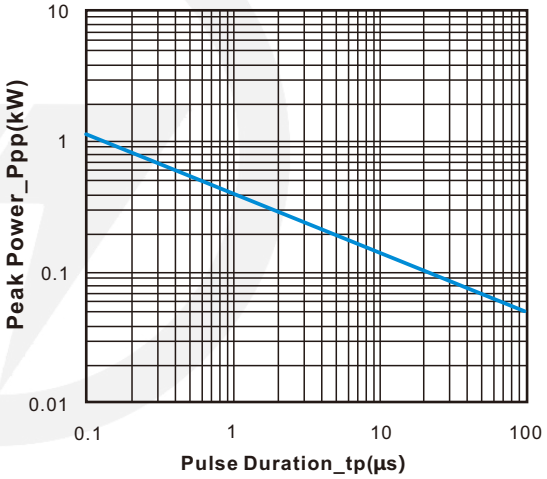
Electrical Characteristics(TA=25°C unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V_{RWM}			5	V	
Breakdown Voltage	V_{BR}	6.5		9.5	V	I_T = 1mA
Reverse Leakage Current	I_R			0.2	uA	V_{RWM} = 5V
Clamping Voltage	V_C			12	V	I_{PP} = 1A (8 x 20μs pulse)
Clamping Voltage	V_C			25	V	I_{PP} = 4A (8 x 20μs pulse)
Junction Capacitance	C_J		0.3	0.5	pF	VR = 0V, f = 1MHz

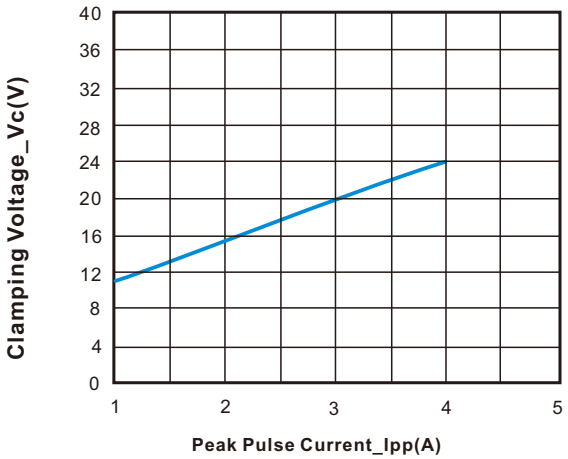
Characteristic Curves



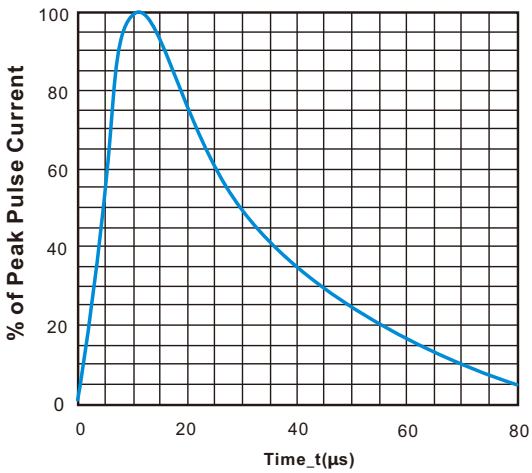
Junction Capacitance vs. Reverse Volatage



Peak Pulse Power vs. Pulse Time



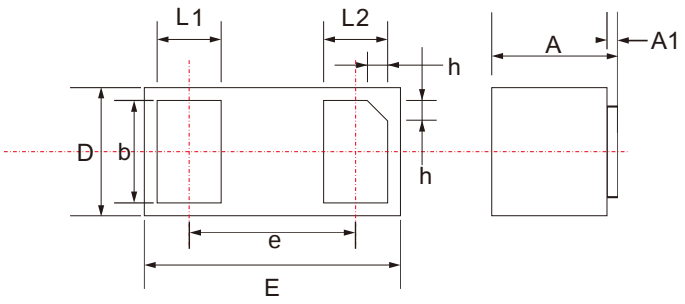
Clamping Voltage vs. Peak Pulse Current(tp=8/20μs)



8x20μs Pulse Waveform

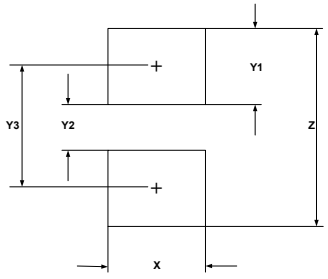
DFN-1006 Package Outline

Unit : mm



SYMBOL	DIMENSIONS	
	MIN.	MAX.
D	0.550	0.650
E	0.950	1.050
L1	0.200	0.300
L2	0.200	0.300
b	0.450	0.550
e	0.650 TYP.	
A	0.450	0.550
A1	0.000	0.050
h	0.070	0.170

DFN-1006 Suggested Pad Layout

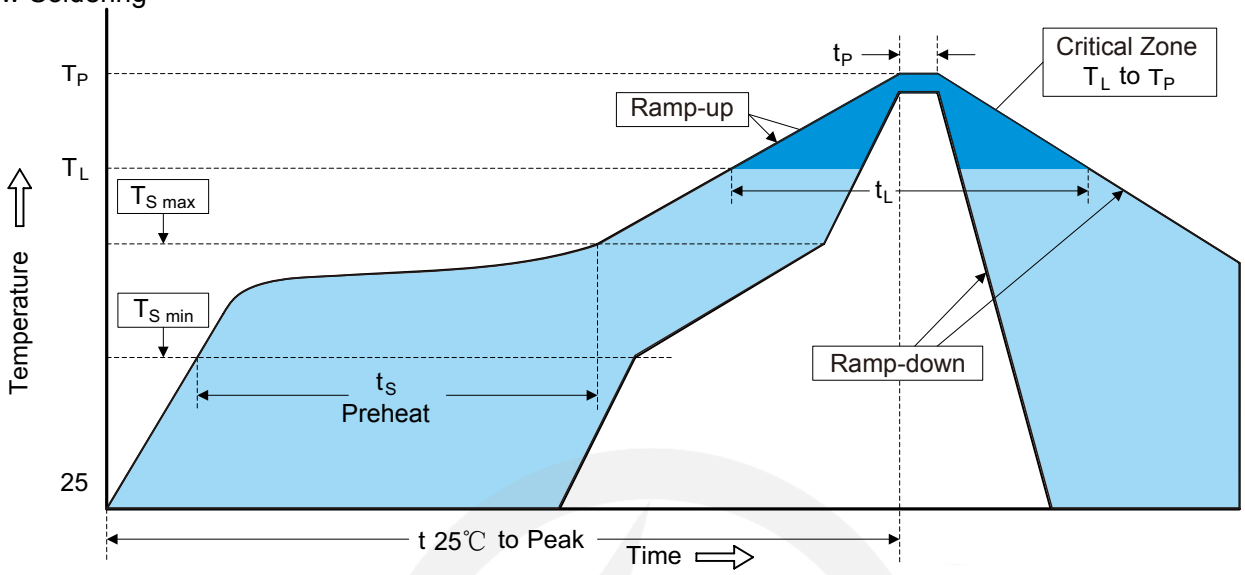


SYM	DIMENSIONS
	MILLIMETERS
X	0.60
Y1	0.50
Y2	0.30
Y3	0.80
Z	1.30

Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm
3.The pad layout is for reference purpose only.

Recommended Soldering Conditions

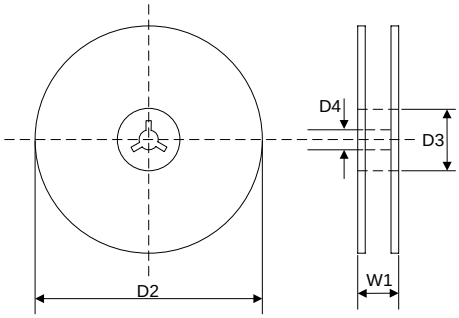
Reflow Soldering



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3℃/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_S)	 150℃ 200℃ 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	 3℃/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	 217℃ 60-150 seconds
Peak Temperature (T_P)	260℃
Time within 5℃ of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8 minutes max.

7” Reel



D2	Φ178.0±2.0
D3	Φ50.0Min.
D4	Φ13.0±0.5
W1	16.0±2.0
Quantity: 10000PCS	